

Product Data Sheet

Tacky Paste Flux (TPF)

Product Description

- Touch-up and rework
- Attachment of BGA spheres
- Soldering Flip Chip components
- Excellent wetting compatibility
- Wide reflow window
- Compatible with most board finishes

Flux Type

AMTECH Tacky Paste Flux	Type	Class
SynTECH-TPF	N/C	RELO
SynTECH-LF-TPF	N/C for LF	RELO
NC-559-TPF	N/C	RELO
LF-4300-TPF	N/C & W/S	RELO
4300-TPF	N/C & W/S	RELO
NC-559-ASM-TPF	N/C	RELO
WS-488-TPF	W/S	ROLO
NWS-4100-TPF	W/S	REMO
NWS-4200-TPF	W/S	REMO
NWS-4200-4-TPF	W/S	REHO
NWS-4200-6-TPF	W/S	REMO
NWS-4200-LF-TPF	W/S for LF	REMO
RMA-223-TPF	RMA	REMO
RMA-223-LF-TPF	RMA for LF	REMO
RA-223	RA	REHO

Stencil Life

>8 hrs. @ 20-50% RH & 22-28°C
 ~4 hrs. @ 50-70% RH & 22-28°C

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA) works well.

Storage and Handling Procedures

Refrigerated storage at 42–47°F will prolong Tacky Paste Flux's shelf life to no less than 1 year. Syringes & cartridges should be stored vertically with the dispensing tip down. Tacky Paste Flux should be allowed to reach ambient temperature naturally, prior to use (about 6-8 hours). NEVER FREEZE TACKY PASTE FLUX.

Available Packaging

Standard packaging for stencil printing and dispensing applications include:
 75 & 150 gram jars
 150 gram cartridges
 10cc & 30cc syringes

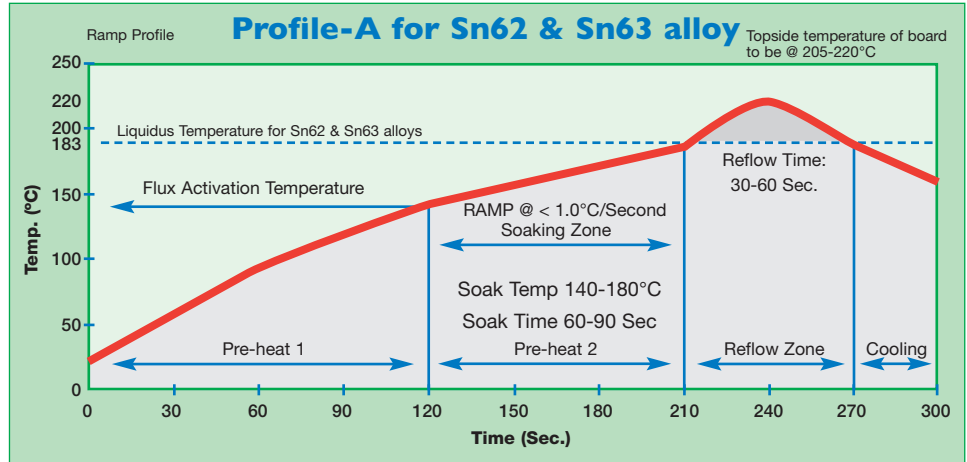
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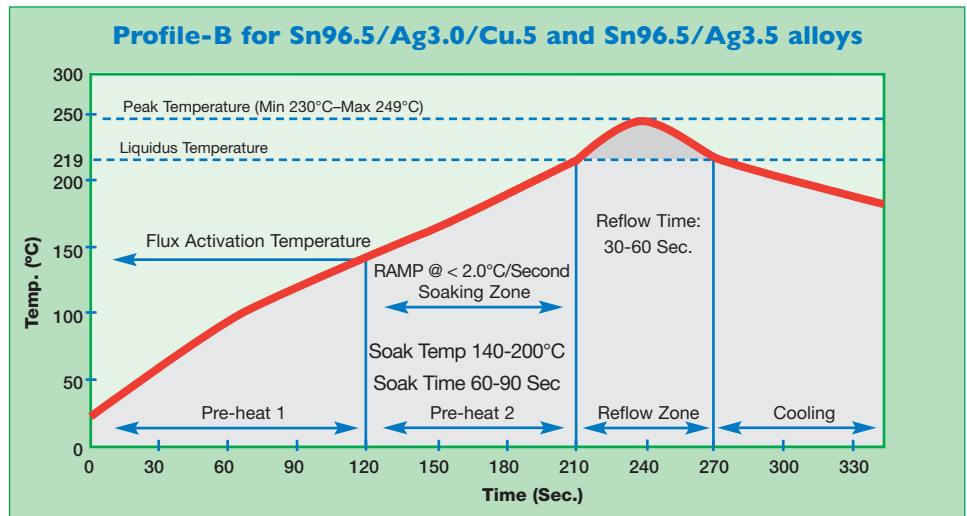
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Recommended Profiles:

Profile-A was designed to serve as a starting point for process optimization using Tacky Paste Flux. A cool down rate of (-) 2–4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn63 or Sn62 alloys.



Profile-B was designed to serve as a starting point for process optimization using Tacky Paste Flux. A cool down rate of (-) 2 - 4°C/second is ideal for the formation of a fine grain structure without risking damage to thermally sensitive components. This profile is recommended when soldering Sn96.5/Ag3.0/Cu.5 or Sn96.5/Ag3.5 alloys.



The information contained herein is based on technical data that we believe to be reliable and is intended for use by persons having technical skill, at their own risk. Users of our products should make their own tests to determine the suitability of each product for their particular process. AMTECH will assume no liability for results obtained or damages incurred through the application of the data presented.

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